



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-06-04
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HSDK*Z20Q01U	A	SHENZHEN B/E	2015-06-04
Amount	UoM	Unit type	ST ECOPACK Grade	
1860	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	10.2, 16.25, 4.5	2	THROUGH HOLE	
Comment	Package: DO 220,MD valid for CP:STPS10L60D.			

QueryList : ROHS directive 2011/65/EU _ July 2011

Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
5 - Product(s) is obsolete, no information is available		false
6 - Product(s) is unknown, no information is available		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	

QueryList : REACH-17th December 2014

Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HSDK*Z20Q01U					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (chose)	Other inorganic materials	5.248	mg	supplier	die	Silicon (Si)	7440-21-3		5.078	mg	967607	2730
				supplier	metallization	Aluminium (Al)	7429-90-5		0.105	mg	20008	56
				supplier	Passivation	Silicon Oxide	7631-86-9		0.021	mg	4002	11
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.002	mg	381	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	1334	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.035	mg	6669	19
Leadframe	Copper & its alloys	1184.310	mg	supplier	alloy	Copper (Cu)	7440-50-8		1182.771	mg	998701	635898
				supplier	alloy	Iron (Fe)	7439-89-6		1.184	mg	1000	637
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.355	mg	300	191
Soft solder	Solder	4.953	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	4.730	mg	954977	2543
				supplier	solder	Silver (Ag)	7440-22-4		0.124	mg	25035	67
				supplier	solder	Tin (Sn)	7440-31-5		0.099	mg	19988	53
Bonding wires	Other inorganic materials	2.025	mg	supplier	wire	Aluminium (Al)	7429-90-5		2.025	mg	1000000	1089
Encapsulation	Other Organic Materials	659.223	mg	supplier	mold compound	Silica, vitreous	60676-86-0		573.524	mg	870000	308346
				supplier	mold compound	Epoxy resin	Proprietary		65.922	mg	100000	35442
				supplier	mold compound	Phenol resin	Proprietary		16.481	mg	25001	8861
				supplier	mold compound	Carbon Black	1333-86-4		3.296	mg	5000	1772
connections coating	Solder	4.241	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		4.241	mg	1000000	2280